

Amendments to the Claims

1. (Currently Amended) An interposer for electrically coupling a semiconductor device to an electrical apparatus, the interposer comprising:

an electrically insulative substrate for removable coupling to an ~~electric~~-electrical apparatus, said substrate having a portion that has a uniform thickness, and said portion having a planar surface, said planar surface being part of a substrate outermost surface for receiving thereover a semiconductor device such that said semiconductor device lies at least in part over said outermost surface and is unimbedded into said substrate; and

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an electrical conductor on the planar surface of the portion of the electrically insulative substrate, the electrical conductor having a receiving end on the planar surface of the portion of the electrically insulative substrate for connecting to a said semiconductor device at electrically conductive terminals of said semiconductor device and such that at least some of said terminals are located in the region between said semiconductor device and said outermost surface of said substrate, and a terminal end on the planar surface of the portion of the electrically insulative substrate for connecting to ~~an~~ said electrical apparatus, such that the coupling of said substrate to said ~~electric~~-electrical apparatus structurally supports said substrate with said terminal end in electric contact with said electric apparatus.

2. (Previously Amended) An interposer as recited in claim 1, wherein the substrate comprises crystalline glass.

4. (Original) An interposer as recited in claim 1, wherein the receiving end protrudes upwardly with respect to the substrate.

6. (Previously Amended) An interposer as recited in claim 1, wherein the substrate comprises a material selected from the group consisting of glass, alumina, glass ceramic, nonmetallic nitride, aluminum nitride, nonmetallic carbide, and mixtures thereof.

7. (Previously Amended) An interposer as recited in claim 1, wherein the substrate comprises a nitride.

FI 8. (Original) An interposer as recited in claim 1, wherein the interposer further comprises an electrically insulating layer on a portion of the conductor between the receiving end and the terminal end.

9. (Previously Amended) An interposer as recited in claim 7, wherein the nitride comprises boron nitride.

10. (Currently Amended) An interposer for electrically coupling a semiconductive device to an electrical apparatus, the interposer comprising:

a sheet for removable coupling to an electrical apparatus, said sheet having a portion that has a uniform thickness, and said sheet comprised of an electrically insulating material, said sheet having an outermost surface for receiving thereon a semiconductive device such that said semiconductive device lies at least in part on said outermost surface and is unimbedded into said ~~substrate~~sheet; and

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an electrical conductor on the portion, the electrical conductor having a receiving end on said portion for connecting to ~~a~~said semiconductive device at electrically conductive terminals of said semiconductive device such that at least some of said terminals are located in the region between said semiconductive device and said outermost surface of said sheet, and a terminal end on said portion for connecting to ~~an~~said electrical apparatus, such that the semiconductive device is electrically coupled to the electrical apparatus when the semiconductive device is connected to the receiving end of the electrical conductor and the terminal end of the electrical conductor is connected to the electrical apparatus, such that the coupling of said sheet to said ~~electric~~electrical apparatus structurally supports said sheet with said terminal end in electric contact with said electrical ~~electric~~ apparatus.

11. (Previously Amended) An interposer as recited in claim 10, wherein the material comprises alumina.

12. (Previously Amended) An interposer as recited in claim 10, wherein the material comprises crystallized glass.


13. (Currently Amended) An interposer for electrically coupling a semiconductive device to an electrical apparatus, the interposer comprising:

an electrically insulative sheet for removable coupling to an electrical apparatus, said sheet having a portion that has a uniform thickness, and said portion being composed of a material selected from the group consisting of devitrified ceramics, vitro ceramics, single oxide ceramics, and mixed oxide ceramics, and mixtures thereof, said sheet having an outermost surface for receiving thereon a semiconductive device such that said semiconductive device lies at least in part on said outermost surface and is unimbedded into said ~~substrate~~sheet; and

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an electrical conductor on said portion, the electrical conductor having a receiving end on said portion for connecting to a said semiconductive device at electrically conductive terminals of said semiconductive device such that at least some of said terminals are located in the region between said semiconductive device and said outermost surface of said sheet, and a terminal end on said portion for connecting to ~~an~~ said electrical apparatus, such that the semiconductive device is electrically coupled to the electrical apparatus when the semiconductive device is connected to the receiving end of the electrical conductor and the terminal end of the electrical conductor is connected to the electrical apparatus, such that the coupling of said sheet to said electrical ~~electric~~ apparatus structurally supports said sheet with said terminal end in electric contact with said electrical ~~electric~~ apparatus.

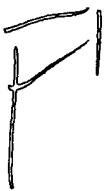
14. (Currently Amended) An interposer for electrically coupling a semiconductive device to an electrical apparatus, the interposer comprising:

an electrically insulative sheet for removable coupling to an electrical apparatus, said sheet having a portion that has a uniform thickness, and said portion being composed of an electrically insulating material selected from the group consisting of alumina, alumina with silica, alumina with silicates, alumina with derivatives of silicates, and mixtures thereof, said sheet having an outermost surface for receiving thereon a semiconductive device such that said semiconductive device lies at least in part on said outermost surface and is unimbedded into said ~~substrate~~sheet; and

 an electrical conductor on said portion, the electrical conductor having a receiving end on said portion for connecting to ~~a~~said semiconductive device at electrically conductive terminals of said semiconductive device such that at least some of said terminals are located in the region between said semiconductive device and said outermost surface of said sheet, and a terminal end on said portion for connecting to ~~an~~said electrical apparatus, such that the semiconductive device is electrically coupled to the electrical apparatus when the semiconductive device is connected to the receiving end of the electrical conductor and the terminal end of the electrical conductor is connected to the electrical apparatus, such that the coupling of said sheet to said electrical ~~electric~~-apparatus structurally supports said sheet with said terminal end in electric contact with said electrical ~~electric~~-apparatus.

15. (Currently Amended) An interposer for electrically coupling a semiconductive device to an electrical apparatus, the interposer comprising:

an electrically insulative sheet for removable coupling to an electrical apparatus, said sheet having a portion that has a uniform thickness, and said portion being composed of an electrically insulating material selected from the group consisting of boron nitrides, aluminum nitrides, and mixtures thereof, said sheet having an outermost surface for receiving thereon a semiconductive device such that said semiconductive device lies at least in part on said outermost surface and is unimbedded into said ~~substrate~~sheet; and



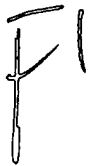
an electrical conductor on said portion, the electrical conductor having a receiving end on said portion for connecting to ~~a~~said semiconductive device at electrically conductive terminals of said semiconductive device such that at least some of said terminals are located in the region between said semiconductive device and said outermost surface of said sheet, and a terminal end on said portion for connecting to ~~an~~said electrical apparatus, such that the semiconductive device is electrically coupled to the electrical apparatus when the semiconductive device is connected to the receiving end of the electrical conductor and the terminal end of the electrical conductor is connected to the electrical apparatus, such that the coupling of said sheet to said electrical ~~electric~~ apparatus structurally supports said sheet with said terminal end in electric contact with said electrical ~~electric~~ apparatus.

39. (Previously Added) An interposer as recited in claim 7, wherein the nitride comprises nonmetallic nitride.

40. (Previously Added) An interposer as recited in claim 1, wherein the substrate comprises a carbide.

41. (Previously Amended) An interposer as recited in claim 40, wherein the carbide comprises nonmetallic carbide.

42. (Previously Added) The interposer as defined in Claim 13, wherein:
the portion of the sheet has a planar surface;
the electrical conductor is on the planar surface of the portion of the sheet;
the receiving end is on the planar surface of the portion of the sheet; and
the terminal end is on the planar surface of the portion of the sheet.



43. (Previously Added) The interposer as defined in Claim 14, wherein:
the portion of the sheet has a planar surface;
the electrical conductor is on the planar surface of the portion of the sheet;
the receiving end is on the planar surface of the portion of the sheet; and
the terminal end is on the planar surface of the portion of the sheet.

44. (Previously Added) The interposer as defined in Claim 15, wherein:
the portion of the sheet has a planar surface;
the electrical conductor is on the planar surface of the portion of the sheet;
the receiving end is on the planar surface of the portion of the sheet; and
the terminal end is on the planar surface of the portion of the sheet.

45. (Currently Amended) An interposer for electrically coupling a semiconductive device to an electrical apparatus, the interposer comprising:

an electrically insulative substrate for removable coupling to an electrical ~~electric~~ apparatus, said substrate being comprised of a material selected from the group consisting of crystalline glass, nitride, and carbide, and mixtures thereof, said substrate having an outermost surface for receiving thereon a semiconductive device such that said semiconductive device lies at least in part on said outermost surface and is unimbedded into said substrate; and

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an electrical conductor on the substrate, the electrical conductor having a receiving end for connecting to ~~a~~said semiconductive device at electrically conductive terminals of said semiconductive device such that at least some of said terminals are located in the region between said semiconductive device and said outermost surface of said substrate, and a terminal end for connecting to ~~an~~said electrical apparatus, such that the coupling of said substrate to said electrical apparatus structurally supports said substrate with said terminal and in electrical contact with said electrical apparatus.

46. (Previously Amended) The interposer as defined in Claim 45, wherein the nitride is a nonmetallic nitride.

47. (Previously Amended) The interposer as defined in Claim 45, wherein the nonmetallic nitride is boron nitride.

48. (Previously Amended) The interposer as defined in Claim 45, wherein the carbide is a nonmetallic carbide.

49. (Currently Amended) An interposer as recited in claim 1, wherein the ~~electrical~~ electric apparatus is selected from the group consisting of a computer, a program logic controller, an electronic game assembly, and a controlling module.

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Cont • 50. (Currently Amended) An interposer as recited in claim 1, wherein the ~~electrical~~ electric apparatus comprises a testing apparatus that monitors, tests, or evaluates the semiconductive device.

51. (Cancelled).

52. (Currently Amended) An interposer for electrically coupling a semiconductive device to an electrical apparatus, the interposer comprising:

a substrate for coupling to an electric apparatus, the electrical ~~electric~~-apparatus selected from the group consisting of a computer, a program logic controller, an electronic game assembly, a controlling module, and a testing apparatus which monitors, tests, or evaluates the semiconductive device, the substrate having a planar surface, said planar surface being part of a substrate outermost surface for receiving thereover a semiconductive device such that said semiconductive device lies at least in part over said outermost surface and is unimbedded into said substrate; and

an electrical conductor on the planar surface of the portion of the electrically insulative substrate, the electrical conductor having:

a receiving end on the planar surface of the portion of the electrically insulative substrate for connecting to a said semiconductive device at electrically conductive terminals of said semiconductive device and such that at least some of said terminals are located in the region between said semiconductive device and said outermost surface of said substrate, and

a terminal end on the planar surface of the portion of the electrically insulative substrate for coupling to the electrical apparatus, such that the coupling of said substrate to said electrical ~~electric~~-apparatus puts said terminal end in electric contact with said electrical ~~electric~~-apparatus and structurally supports said substrate.